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Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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APPROVAL SHEET

RFBPF 2012(0805) Series – RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER

Halogens Free Product

5GHz ISM Band Working Frequency

P/N:RFBPF2012100KST

*Contents in this sheet are subject to change without prior notice

Approval sheet



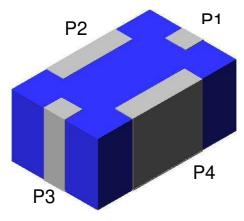
FEATURES

- 1. Multilayer LTCC (Low Temperature Cofired Ceramics) Technology
- 2. Reflow solderable
- 3. Miniatured Size 2.0 x 1.25 x 0.95 mm³
- 4. Low Insertion Loss 0.8dB designed for 5GHz application
- 5. High rejection rate at 2nd harmonics (-20dB @ 11GHz)
- 6. Broad bandwidth coverage from 4.9GHz to 5.95GHz

APPLICATIONS

- 1. Frequency selection and noise suppresion
- 2. 5GHz WLAN 802.11a, HiperLAN2

CONSTRUCTION



PIN	Connection		
P1	Input/Output port		
P2	GND		
P3	Input/Output port		
P4	GND		

Fig 1. Outline of 5GHz Band Pass Filter

DESCRIPTION

Walsin Technology Corporation develops a new ceramic Band Pass Filter specified for 5GHz ISM Band application, as shown in Fig.1. Today, the 5GHz ISM band allocations include USA U-NII band (5.150GHz~ 5.825GHz), Europe HiperLan and ISM (5.150GHz~ 5.875GHz), Japan (4.90GHz~ 5.10GHz), and IEEE802.11a WLAN (5.150GHz~ 5.825GHz). To fulfil the in-band and out-band frequency requirements, this Band Pass Filter has been designed to a high suppression on 2nd harmonic as well as low insertion loss characteristics through Walsin's advanced LTCC (Low Temperature Co-fired Ceramic) technology and superior product design via 3D EM Simulation Skill.

This Band Pass Filter has a rectangular ceramic body with a tiny dimension of $2.0 \times 1.25 \times 0.95 \text{ mm}^3$ future meet the SMT automation and miniaturization requirements on modern portable devices.

Figure			Symbol	Dimension
			L	2.00 ± 0.15 mm
	W	1.25 ± 0.15 mm		
1		4	Т	0.95 ± 0.10 mm
Σ Σ		A	0.25 ± 0.15 mm	
		В	0.25 ± 0.10 mm	
		С	0.25 ± 0.10 mm	
E D		D	0.25 ± 0.15 mm	
		E	1.00 ± 0.15 mm	

DIMENSIONS



Approval sheet

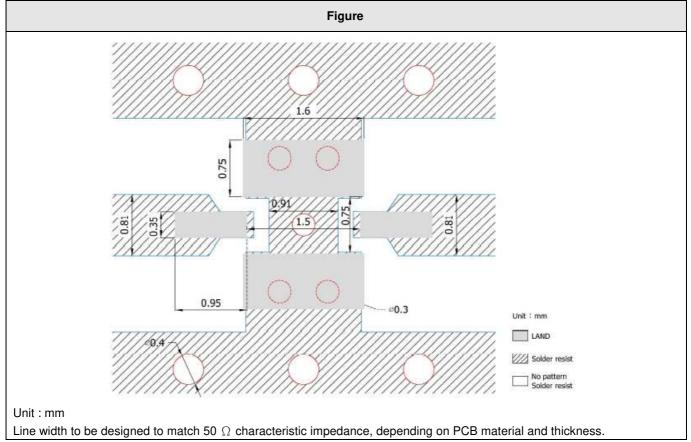
ELECTRICAL CHARACTERISTICS

RFBPF2012100KST	Specification
Frequency range	5400 ± 500 MHz
	1.5dB @ 4.90GHz
Insertion Loss	1.5dB @ 5.25GHz
	1.5dB @ 5.85GHz
VSWR	2.0 max
Ripple	0.6 dB
Attenuation (min)	30 dB @ 3450 MHz
Attenuation (min.)	20dB @ 11000 MHz
Operation Temperature Range	-40°C ~ +100°C

Typical Electrical Chart



SOLDER LAND PATTERN





Approval sheet

RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6	*Solder bath temperature : $235 \pm 5^{\circ}$ C *Immersion time : 2 ± 0.5 sec	At least 95% of a surface of each terminal electrode must be covered by fresh solder.
JESD22-B102D	*Solder : Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : 260 ± 5°C *Leaching immersion time : 30 ± 0.5 sec *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	 *Preheating temperature : 120~150°C, 1 minute. *Solder temperature : 270±5°C *Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs 	No mechanical damage. Samples shall satisfy electrical specification after test. Loss of metallization on the edges of each electrode shall not exceed 25%.
Drop Test JIS C 0044	*Height : 75 cm *Test Surface : Rigid surface of concrete or steel. *Times : 6 surfaces for each units ; 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Samples shall satisfy electrical specification after test.

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Temperature cycle	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.
JIS C 0025	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical
	3. 30±3 minutes at +85°C±3°C,	specification after test.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles	
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Vibration	*Frequency : 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude : 1.5mm	Samples shall satisfy electrical specification
	*Test times : 6hrs.(Two hrs each in three	after test.
	mutually perpendicular directions)	
High temperature	*Temperature : 85°C±2°C	No mechanical damage.
JIS C 0021	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
Humidity	*Humidity : 90% to 95% R.H.	No mechanical damage.
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical specification
JIS C 0022	*Time : 1000+24/-0 hrs.	after test.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
	% 500hrs measuring the first data then	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
L	1	

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

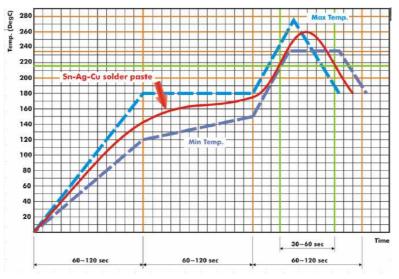


Fig 2. Infrared soldering profile

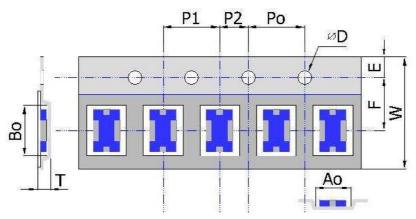
ORDERING CODE

RF	BPF	201210	0	К	S	Т
Walsin	Product Code	Dimension code	Unit of	Application	Specification	Packing
RF device	BPF:	Per 2 digits of	dimension	K: ISM 5.2/5.8	Design Code	T : Reeled
	Band Pass Filter	Length, Width,	0: 0.1 mm	Dual Band		
		Thickness:	1: 1.0 mm			
		e.g. :				
		201210 =				
		Length 20,				
		Width 12,				
		Thickness 10				

Minimum Ordering Quantity: 2000 pcs per reel.

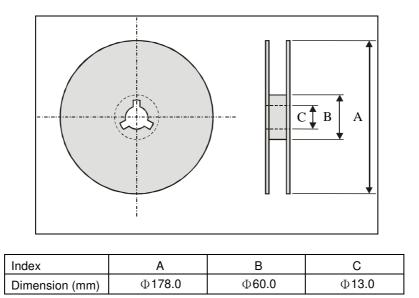
PACKAGING

Plastic Tape specifications (unit :mm)



Index	Ao	Во	ΦD	Т	W
Dimension (mm)	1.52 ± 0.10	2.35 ± 0.10	1.55 ± 0.10	1.12 ± 0.10	8.0 ± 0.30
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10

Reel dimensions



Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.
 - Temperature : -10 to +40°C
 - Humidity : 30 to 70% relative humidity
 - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
 - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
 - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
 - Products should be storage under the airtight packaged condition.